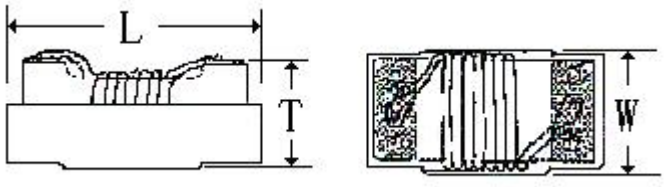
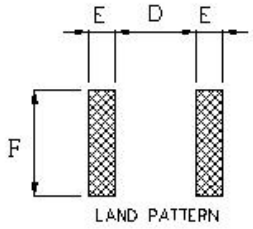
SHAPE & DIMENSION (UNIT:mm)



CODE	L	W	T	E	F	D
DIMENSION	2.92MAX	2.70MAX	2.23MAX	1.02Typ.	2.54Typ.	1.27Typ.

Marking Code: Size: Color: typeface:

PAD LAYOUT(MM):



ELECREICAL SCHEMATIC:

ELECREICAL SPECIFICATION

MEAS. ITEM	SPEC.				TEST FREQ.	CONDITIONS
L	33	μH	±	10%	2.50MHz/0.5V	Ta=25℃，Idc=0A HP4286A
Q	10		Min		2.50MHz/0.5V	HP4286A
DCR	7.0	Ω	Max			Ta=25℃ 502BC
Isat	200	mA	Max			△≦40℃ VR116+VR7210
SRF	12	MHz	Min			E5071C ENA

GENERAL SPECIFICATION

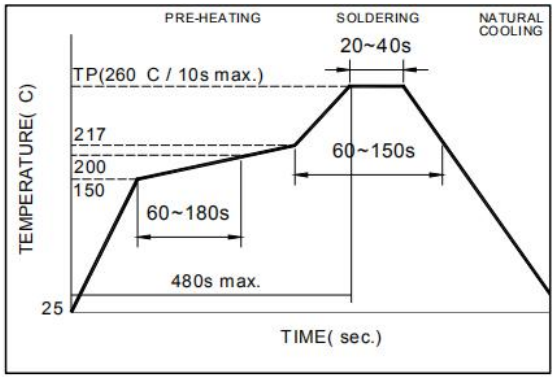
Electrical specifications ：	at 25℃
Operation Temperature：	-40~+125℃
Storage Temperature：	-40~+125℃

Reliability Test

No.	Item	Specification	Test Method
1	Temperature Shock.	Appearance: No damage. Inductance: within ±10% of initial.	Temperature: -25±2℃~+105±2℃ Kept for 30 minutes. Transition time : 5 minutes. 100 Cycles.
2	Humidity Resistance.	Appearance: No damage. Inductance: within ±10% of initial.	Temperature: 40±2℃. Relative Humidity: 90%. Duration: 500 +4/-0 hours.
3	High Temperature Resistance.	Appearance: No damage. Inductance: within ±10% of initial.	Temperature: 105±2℃. Duration: 1000 +4/-0 hours.
4	Low Temperature Resistance.	Appearance: No damage. Inductance: within ±10% of initial.	Temperature: -25±2℃. Duration: 1000 +4/-0 hours.
5	Vibration test.	Appearance: No damage. Inductance: within ±10% of initial.	Oscillation Frequency: 10Hz to 55Hz to 10Hz in 60 seconds as a period. Total amplitude: 1.5mm. Testing Time: a period of 2 hours in each 3 mutually perpendicular directions (total of 6 hours).
6	Solderability Heat test.	Appearance: No damage. Inductance: within ±10% of initial.	Solder temperature: 260 +0/-5℃. Duration: 5 sec. Allowed reflow time: 2 times.
7	Solderability test.	90% or more of electrode area shall be coated by new solder.	Preheating: 160℃,60sec. Solder temperature: 245±5℃. Duration : 5 sec.
8	Flexure Strength.	No visible mechanical damage.	Flexure: 2mm. Pressurizing Speed: 0.5mm/sec. Keep time: 30±1sec.
9	Terminal Strength.	No visible mechanical damage.	Force: 0.45Kg for 0603 series. Force: 0.9Kg for 0805 series. Force: 1.8Kg for 1008 series above. Keep time: 5 sec, X,Y directs.

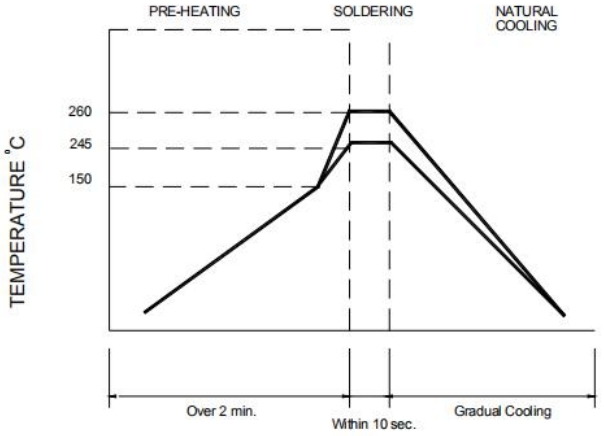
SOLDERING CONDITIONS

Figure 1. Re-flow Soldering (Lead Free)



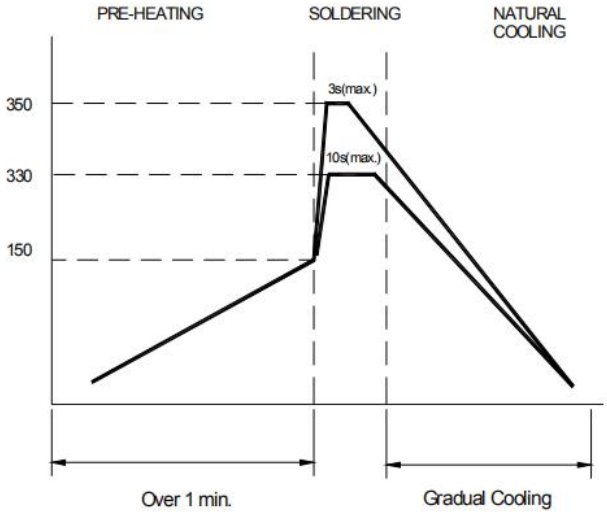
Note:
- Preheat circuit and products to 150℃
- 260℃ tip temperature (max)
- Reflow times: no more than 2 times
- Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

Figure 2. Wave Soldering



Note：
- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)

Figure 3. Hand Soldering

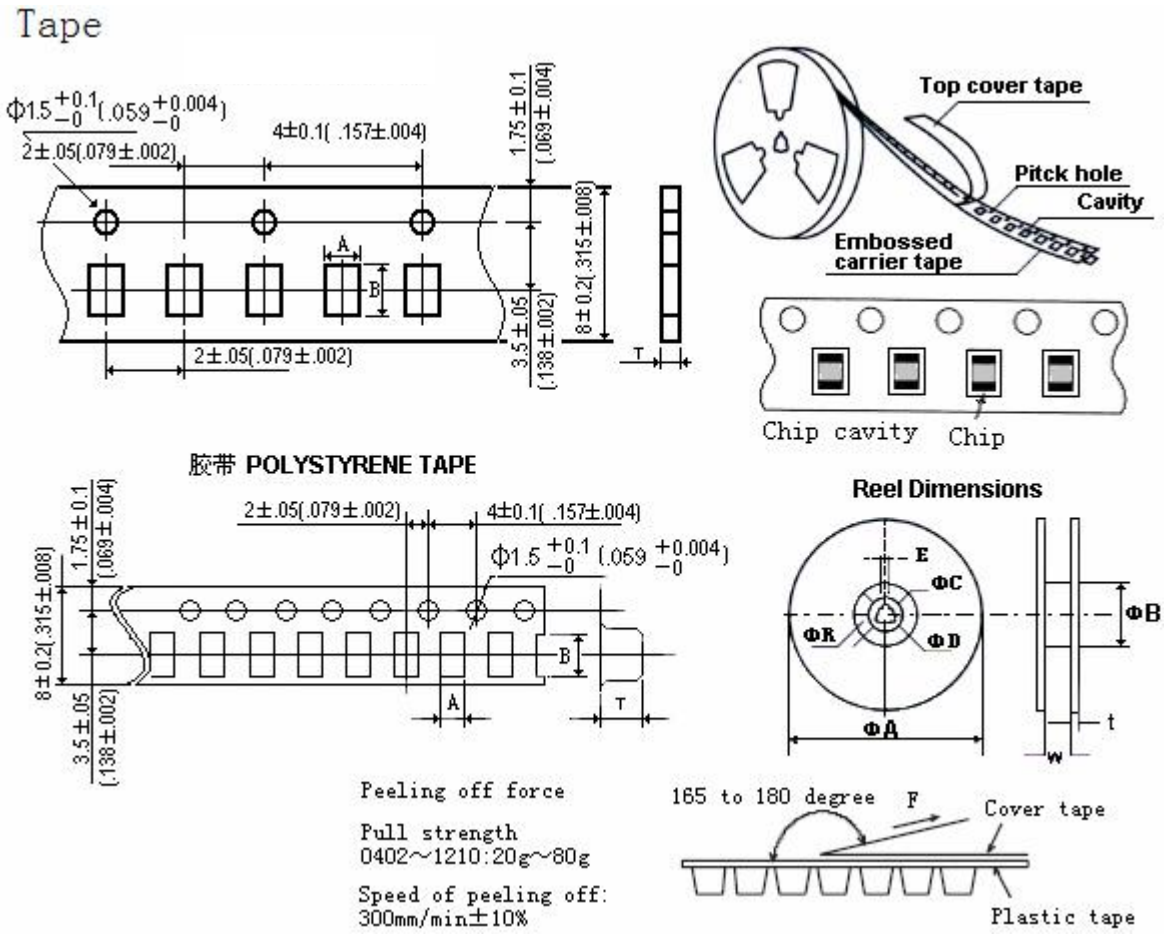


Note:
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 3 sec.

TEST DATA FOR PREPRODUCTION SAMPLE

TEST RESOLUTION					DIMENSION (Unit：mm)		
MEAS.	L	D.C.R	Q		L	W	T
ITEM	uH	Ω			mm	mm	mm
SPEC.	33	7.0	10		2.92MAX	2.70Max	2.23Max
	±						
	10%	Max	Min				
TEST FREQ.	2.5MHz/ 0.5V	at 25℃	2.5MHz/ 0.5V				
1	32.95	5.97	13.0		2.83	2.44	2.04
2	33.11	5.96	12.0		2.83	2.45	2.03
3	32.99	5.98	13.0		2.82	2.44	2.05
4	33.10	5.99	14.0		2.83	2.43	2.04
5	33.13	5.97	14.0		2.81	2.43	2.03
6	33.12	5.96	14.0		2.83	2.44	2.04
7	33.16	5.97	13.0		2.81	2.43	2.05
8	33.16	5.97	13.0		2.82	2.44	2.05
9	32.96	5.97	12.0		2.82	2.43	2.04
10	32.89	5.99	13.0		2.82	2.45	2.05
AVG.	33.06	5.97	13.10		2.82	2.44	2.04
R	0.27	0.03	2.00		0.02	0.02	0.02

PACKAGING



PACKAGING QUANTITY	**2000PCS/RELL**

Type	ΦA	ΦB	ΦC	ΦD	E	W	t	R
0402 ~ 1210	178	60	13	21	2	8.4	2	1